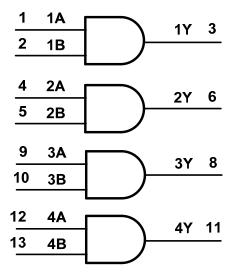


Pin Descriptions

Pin Number	Pin Name	Description
1	1A	Data Input
2	1B	Data Input
3	1Y	Data Output
4	2A	Data Input
5	2B	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3B	Data Input
11	4Y	Data Output
12	4A	Data Input
13	4B	Data Input
14	Vcc	Supply Voltage

Logic Diagram



Function Table

Inp	Output	
Α	В	Υ
L	X	L
X	L	L
Н	Н	Н

Absolute Maximum Ratings (Note 5) (@TA = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +7.0	V
VI	Input Voltage Range	-0.5 to +7.0	V
I _{IK}	Input Clamp Current V _I < 0V	-20	mA
I _{OK}	Output Clamp Current Vo<-0V	-50	mA
lo	Continuous Output Current -0.5V < V _O V _{CC} +0.5V	±25	mA
Icc	Continuous Current Through V _{CC}	50	mA
I _{GND}	Continuous Current Through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

Note: 5. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 6) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage	_	2.0	5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	_	0	V _{CC}	V
		2.0V	_	-50	mA
	High-Level Output Current	2.3V to 2.7V	_	-2	μA
Іон		3.0V to 3.6V	_	-6	mA
		4.5V to 5.5V	_	-12	mA
		2.0V	_	50	μA
	Low-Level Output Current	2.3V to 2.7V	_	2	mA
loL	Low-Level Output Current	3.0V to 3.6V	_	6	mA
		4.5V to 5.5V	_	12	mA
		2.3V to 2.7V	_	200	
Δt/ΔV	Input Transition Rise or Fall Rate	3.0V to 3.6V	_	100	ns/V
		4.5V to 5.5V	_	20	
TA	Operating Free-Air Temperature	_	-40	+125	°C

Note:

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Cumbal	Parameter	Test Conditions	V	T _A = -40	to +85°C	T _A = -40 t	to +125°C	Unit
Symbol	Parameter	rest Conditions	V _{CC}	Min	Max	Min	Max	Unit
		_	2.0V	1.5	_	1.5	_	
.,	High-Level Input	_	2.3V to 2.7V	V _{CC} X 0.7	_	V _{CC} X 0.7	_	V
ViH	Voltage	_	3.0V to 3.6V	V _{CC} X 0.7	_	V _{CC} X 0.7	_	V
		_	4.5V to 5.5V	V _{CC} X 0.7	_	V _{CC} X 0.7	_	
		_	2.0V	_	0.5	_	0.5	
VIL	Low-Level Input	_	2.3V to 2.7V	_	V _{CC} X 0.3	_	V _{CC} X 0.3	V
VIL	Voltage	_	3.0V to 3.6V	_	V _{CC} X 0.3	_	V _{CC} X 0.3]
		_	4.5V to 5.5V	_	V _{CC} X 0.3	_	V _{CC} X 0.3	
		I _{OH} = -50μA	2.0V to 5.5V	V _{CC} -0.1	_	V _{CC} -0.1	_	
\ /	High-Level	I _{OH} = -2mA	2.3V	2.0	_	2.0	_	V
V _{OH}	Output Voltage	I _{OH} = -6mA	3.0V	2.48	_	2.48	_	V
		I _{OH} = -12mA	4.5V	3.8	_	3.8	_	
		$I_{OL} = 50\mu A$	2.0V to 5.5V	_	0.1	_	0.1	
V	Low-Level	I _{OL} = 2mA	2.3V	_	0.4	_	0.4	V
V _{OL}	Output Voltage	I _{OL} = 6mA	3.0V	_	0.44	_	0.44	V
		I _{OL} = 12mA	4.5V	_	0.55	_	0.55	
l _{OFF}	Power Down Leakage Current	V_{I} or $V_{O} = 0$ to 5.5V	0V	_	5	_	5	μΑ
l _l	Input Current	V _I =GND or 5.5V	0 to 5.5V	_	±1	_	±1	μA
Icc	Supply Current	$V_1 = GND \text{ or } V_{CC}$ $I_0 = 0$	5.5V	_	20	_	20	μΑ

^{6.} Unused inputs should be held at $V_{\text{\tiny CC}}$ or Ground.



Switching Characteristics

Symbol	Parameter	Test	V		Γ _A = +25°(3	-40°C to	o +85°C	-40°C to	+125°C	Unit
Syllibol		Conditions	V _{CC}	Min	Тур	Max	Min	Max	Min	Max	Ullit
		F: 4	2.5V ± 0.2V	_	7.9	13.8	1	16	1	17	
	Figure 1 $C_L = 15pF$	3.3V ± 0.3V	_	5.6	8.8	1	10.5	1	11.5	ns	
	Propagation	CL = 13pi	5.0V ± 0.5V	_	4.1	5.9	1	7	1	8	
t _{PD}	Delay A _N to Y _N	Eimma 4	2.5V ± 0.2V	_	10.5	17.3	1	20	1	21	
		Figure 1	3.3V ± 0.3V	_	7.5	12.5	1	14	1	15	ns
	$C_L = 50 \text{ pF}$	5.0V ± 0.5V	_	5.5	7.9	1	9	1	10		

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

	Parameter	Test Conditions	V _{CC}	Тур	Unit
0	Power Dissipation	F= 10 MHz	3.3V	8	۲
C _{pd}	Capacitance per Gate	C _L =50pF	5.0V	10	pF

Noise Characteristics

 $V_{CC} = 3V$, $C_L = 50pF T_A = +25°C$

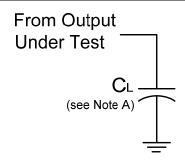
Symbol	I Parameter		Тур	Max	Unit
$V_{OL(p)}$	Quiet Output, Maximum Dynamic V _{OL}		0.2	0.8	V
V _{OL(V)}			-0.1	-0.8	V
V _{OH(V)}	V _{OH(V)} Quiet Output, Minimum Dynamic V _{OH}		3.1	_	V
V _{IH(D)}	V _{IH(D)} High Level Dynamic Input Voltage		_	_	V
V _{IL(D)}	(=)		_	0.99	V

Package Characterisitics

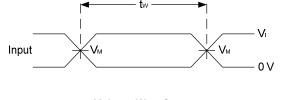
Symbol	Parameter	Test Conditions	V _{cc}	Min	Тур	Max	Unit
Ci	Input Capacitance	$V_i = V_{CC} - \text{or GND}$	2.0V to 5.5V	_	3.3	10	pF



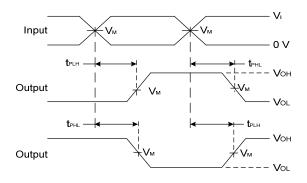
Parameter Measurement Information



V	Inj	outs			
Vcc	VI	t _r /t _f	VM	CL	
2.0V to 5.5V	Vcc	<3ns	V _{CC} /2	15pF or 50pF	



Voltage Waveform **Pulse Duration**



Voltage Waveform Propagation Delay Times **Inverting and Non Inverting Outputs**

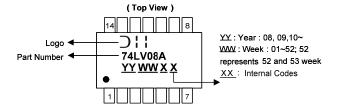
- Notes: A. Includes test lead and test apparatus capacitance.

 B. All pulses are supplied at pulse repetition rate ≤ 10MHz
 C. Inputs are measured separately one transition per measurement
 - D. t_{PLH} and t_{PHL} are the same as t_{PD}

Figure 1 Load Circuit and Voltage Waveforms

Marking Information

(1) SO14, TSSOP14



Part Number Package 5 of 8 www.diodes.com

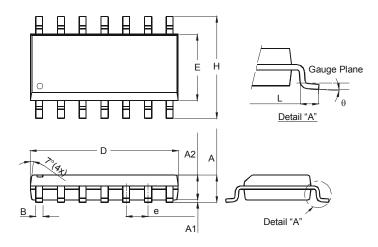


74LV08AS14	SO-14
74LV08AT14	TSSOP-14

Package Outline Dimensions (All dimensions in mm.)

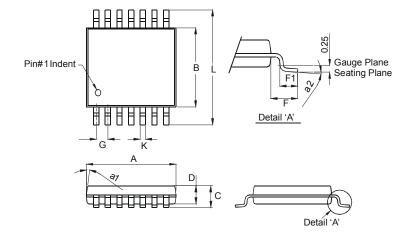
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

Package Type: SO-14



	SO-14						
Dim	Min	Max					
Α	1.47	1.73					
A1	0.10	0.25					
A2	1.45	Тур					
В	0.33	0.51					
D	8.53	8.74					
Е	3.80	3.99					
е	1.27	Тур					
Н	5.80	6.20					
L	0.38	1.27					
θ	0°	8°					
All Di	All Dimensions in mm						

Package Type: TSSOP-14



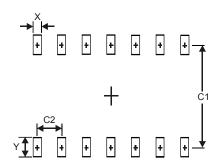
TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
Α	4.9	5.10
В	4.30	4.50
С	_	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
Ĺ	6.40 Typ	
All Dimensions in mm		



Suggested Pad Layout

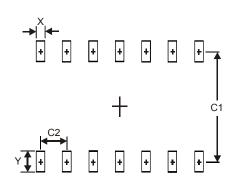
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

Package Type: SO-14



Dimensions	Value (in mm)
Х	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)	
Х	0.45	
Y	1.45	
C1	5.9	
C2	0.65	

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